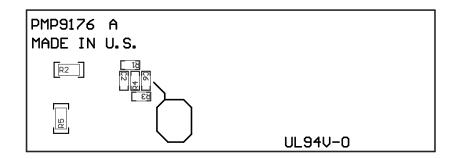


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9176	REV: A	SVN REV	: Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 6/26/2	2018 9:41:28	AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9176	REV: A	SVN REV	: Not In VersionControl	
	Bottom Overlay <- 390NDI				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/26/2	2018 9:41:29	AM	TEXAS INSTRUMENTS	

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